

**AMENDMENTS TO THE SPECIFICATION**

Please amend paragraph [03] as follows:

-- [03] In order to protect the sense die 100 from degrading effects of fluids, a gel (not shown) is applied to cover the surface of the sense die ~~100~~ 112 and wiring 110, metal contacts 104, diaphragm 106, etc. The wires 110 and metal contacts 104 typically include an increased amount of gold or the gold is replaced entirely with platinum. These measures protect the sense die 100, wires 110, and contacts 104 from degradation over time. However, problems become apparent when the pressure medium contains corrosive elements. The corrosive elements tend to infiltrate into the gel, aggressively corroding the wiring bonds, metal contacts 104, and the sensing die 100. --

Please amend paragraph [22] as follows:

-- [22] Conventionally, pressure is sensed from the side of a sensing die maintaining resistor circuitry and metal contacts. However, in the illustrated arrangement, the pressure of the fluid acts on a first side 10 of the sensing die 6, i.e., the side opposite that of the resistors (not shown) and metal contacts 7. The resistors and metal contacts 7 need not be formed on a side opposite the first side, but rather on a side not exposed to the fluid from the vessel. Specifically, fluid flows from vessel 4 through housing aperture 14 and carrier aperture 24, as indicated by flow arrow 5, to the first side 10 of sensing die 6. Changes in pressure cause a change in the crystal structure of sensing die 6, which is detected and processed by associated circuitry to determine the pressure of the fluid contained in vessel 4. The associated circuitry commonly includes an ASIC ~~57~~ 56, resistors and metal contacts 7, wiring 46, conduction paths 58, and the like described in detail below. --